

In The Claims:**Claims 1-19 (canceled)**

20. (original) A package substrate adapted to carry a die of a wire bonding type, the package substrate at least comprising:

a substrate having a surface, a power pad, a ground pad and a signal pad, wherein the surface of the substrate having a die bonding area, the power pad, the ground pad and the signal pad disposed outside the die bonding area;

at least one passive component disposed between the power pad and the ground pad, the passive component having at least two electrodes which are connected to the power pad and the ground pad respectively; and

a metal layer formed on exposed surfaces of the electrodes and exposed surfaces of the power pad, the ground pad and the signal pad.

21. (original) The package substrate of claim 20, further comprising the step of forming a patterned solder mask layer on the surface of the substrate, the patterned solder mask layer exposing the surfaces of the power pad, the ground pad and the signal pad.

22. (original) The package substrate of claim 20, wherein the material of the metal layer is selected from a group consisting of nickel, gold and alloy thereof.

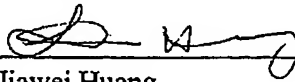
23. (original) The package substrate of claim 20, wherein the passive component is selected from a group consisting of an inductor and a capacitor.

No new matter has been added to the application by the amendments made to the claims.

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